The DUET Series
Dual Interface Milling & Embedding

DUET WirePRO™
Dual Interface Milling & Embedding

- Direct Solder Process
- Cavity Milling
- Module Embedding
- ATR & ATS Testing

Output: 2500-3000 CPH
Voltage: 380VAC 50/60 Hz
Power: 11kW
Compressed Air: 6kg/cm² 220L/min
Dims: [L]4900mm [W]1050mm [H]1950mm
Multimedia: Video Link

DUET WirePRO
Antenna Preparation

DUET WirePRO
Module Embedding

DUET WirePRO
Stations

Developed by Cardmatix, the patented Direct-Solder Process drives the production of over 500 million dual interface banking cards a year. No other process offers the RF performance, longevity, or durability of a solder connection. A direct-solder connection does not impair RF performance, and will not decay or change with time.

The Direct-Solder Method is the process of soldering a copper wire antenna embedded within the card body directly to wire antenna pads on the back of the dual interface module.

Removable Magazines: Attach or detach magazines for easy loading and unloading of cards.

Cavity Milling: The WirePRO is equipped with three cavity milling stations to expose the antenna and then form the final module cavity.

Antenna Preparation: Using vision controlled robotics, the antenna leads are located, QC checked, and pulled from the cavity.

Direct-Solder: Antenna leads are soldered to the dual interface module using thermal compression method.

Wire Dressing: The antenna leads are folded under the module.

Module Embedding - is the process of embedding the module into the card body with the hot-melt glue tape lamination process with three hot-pressers and one cold presser.

Glue Tape: The WirePRO uses traditional hot-melt glue tape commonly available on the market.

ATS: Contactless interface functioning is tested first after antenna connection, and again after module embedding.

ATR: Contact interface functioning is tested after embedding.